

Title (en)

ARRANGEMENT AND METHOD FOR THE REAR-FACED CONTACTING OF A SEMICONDUCTOR SUBSTRATE

Title (de)

ANORDNUNG UND VERFAHREN ZUM RUCKSEITIGEN KONTAKTIEREN EINES HALBLEITERSUBSTRATS

Title (fr)

ENSEMBLE ET PROCEDE DE MISE EN CONTACT COTE ARRIERE D'UN SUBSTRAT SEMI-CONDUCTEUR

Publication

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Application

EP 02714062 A 20020222

Priority

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Abstract (en)

[origin: WO02073663A1] A base body (21) is provided on which a first sealing ring (23) and a second sealing ring (24) are arranged. A substrate (1) is arranged on the sealing rings such that a cavity (25) is formed between the first sealing ring (23), the second sealing ring (24), the base body (21) and the substrate (1). An etching substance for etching a conducting layer applied to the substrate (1) may be introduced into the cavity (25). Should a conducting layer (5), applied to the rear face of the substrate be exposed, an electrolyte can be filled into the cavity (25) which contacts the conducting layer (5) and thus the substrate rear face.

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